

PRODUCT / PROCESS CHANGE NOTIFICATION

To Be Completed By Change Initiator

DATE: August 12, 2016

NOTIFICATION REF: NA

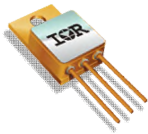
 APPROVAL NOTIFICATION

PRODUCT / PROCESS REFERENCE: Low-ohmic TO-254 package standardization

TYPE OF CHANGE: MAJOR MINOR EDITORIAL PROCESS PRODUCT**DETAILED DESCRIPTION OF CHANGE:**

IR's standard TO-254 package used in Schottky devices is changing to a new low-ohmic TO-254 package type. The low-ohmic TO-254 packages have the same case outline, however the package uses a different lead material with lower resistance; the lead material changes from 52 alloy copper core 3:1, to copper / zirconium.

See list attached for part numbers affected.

**DETAILED REASON FOR CHANGE:**

As a product improvement activity and package standardization, IR is changing from the standard TO-254 package to a low-ohmic package which will enhance product performance, specifically reducing package resistance by an average of 13 mohm.

As of the effectivity date below, all Schottky products in TO-254 packages will be manufactured with one standard low-ohmic package purchased from IR's certified package supplier.

EFFECTIVITY DATE: August 12, 2016

IMPACT OF CHANGE: No change to device specification

Change Initiator:

Kelley Price
Quality Assurance Manager

Approved By:

Paul Hebert
Quality Management Director

QPL Part Numbers;

JANS1N7043CCT1	JANS1N6660CCT1
JANTX1N7043CCT1	JANTX1N6660CCT1
JANTXV1N7043CCT1	JANTXV1N6660CCT1
JANS1N7039CCT1	JANS1N7062CCT1
JANTX1N7039CCT1	JANTX1N7062CCT1
JANTXV1N7039CCT1	JANTXV1N7062CCT1

QIRL Part Numbers;

35CGQ150	35SCGQ060
12CGQ150	35CGQ045
35CGQ100	22CGQ045
15CGQ100	35SCGQ030